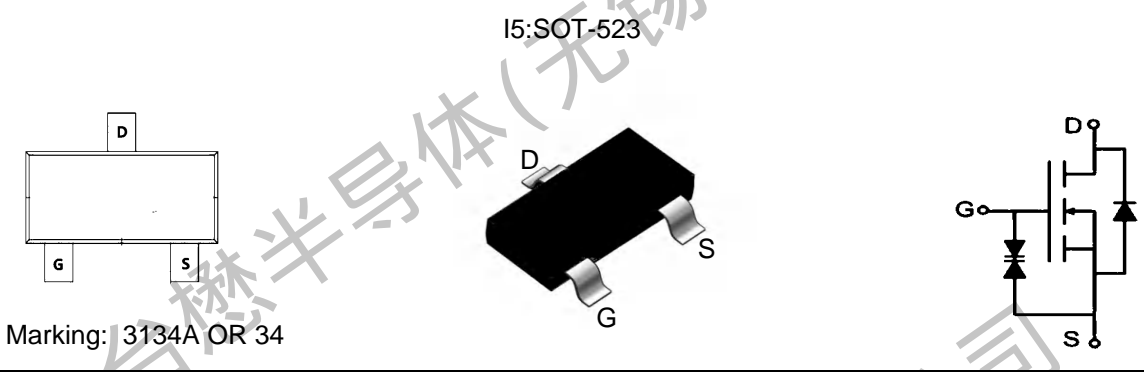




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N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>$V_{DS} = 20V$ $I_D = 1A$ $R_{DS(ON)} = 145 m\Omega (typ.) @ V_{GS} = 4.5V$</p> <p>ESD protection</p> <p>100% UIS Tested 100% R_g Tested</p>
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Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	1	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	0.6	A
I_{DM}	Pulsed Drain Current	2.5	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	0.17	W
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	735	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction Case	---	---	$^\circ C/W$

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Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20V, V_{GS}=0V,$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 10V$	-	-	± 10	μA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.7	0.9	V
$R_{DS(on)}$	Static Drain-Source on-Resistance	$V_{GS}=4.5V, I_D=0.5A$	-	145	190	m Ω
		$V_{GS}=2.5V, I_D=0.4A$	-	225	315	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=10V, V_{GS}=0V,$ $f=1.0MHz$	-	60	-	pF
C_{oss}	Output Capacitance		-	22	-	pF
C_{riss}	Reverse Transfer Capacitance		-	12	-	pF
Q_g	Total Gate Charge	$V_{DS}=10V, I_D=0.75A,$ $V_{GS}=4.5V$	-	1	-	nC
Q_{gs}	Gate-Source Charge		-	0.28	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	0.22	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=10V,$ $I_D=0.5A, R_{GEN}=10\Omega,$ $V_{GS}=4.5V$	-	2	-	ns
t_r	Turn-on Rise Time		-	19	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	10	-	ns
t_f	Turn-off Fall Time		-	23	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	1	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	3	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=0.75A$	-	-	1.2	V

Typical Performance Characteristics

Figure 1: Output Characteristics

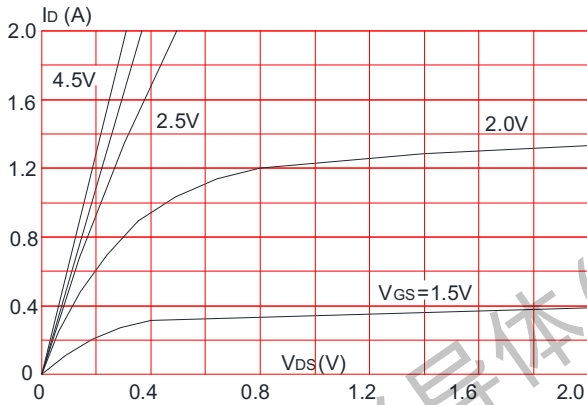


Figure 2: Typical Transfer Characteristics

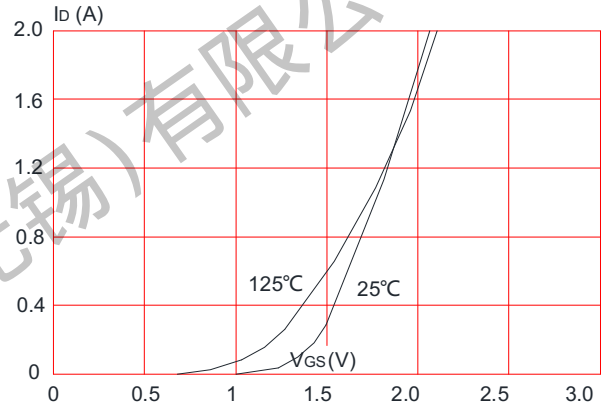


Figure 3: On-resistance vs. Drain Current

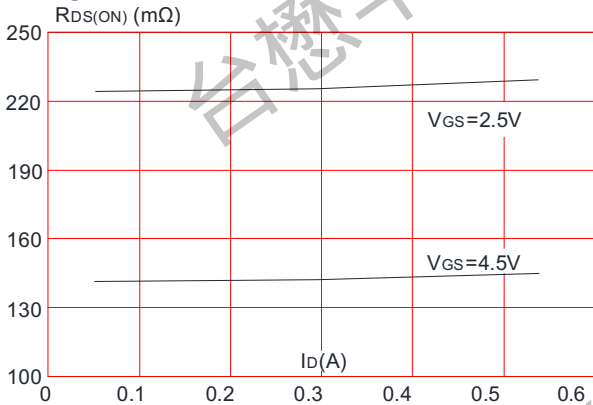


Figure 4: Body Diode Characteristics

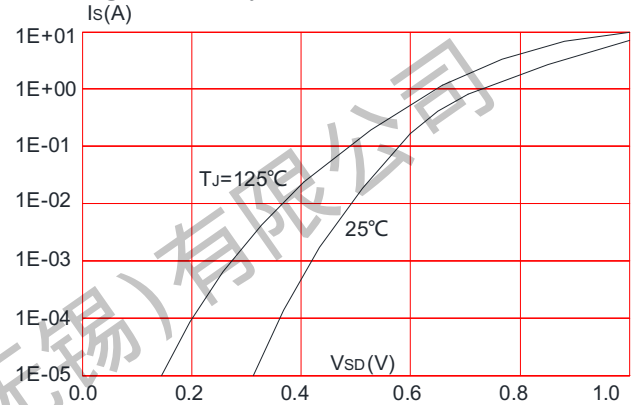


Figure 5: Gate Charge Characteristics

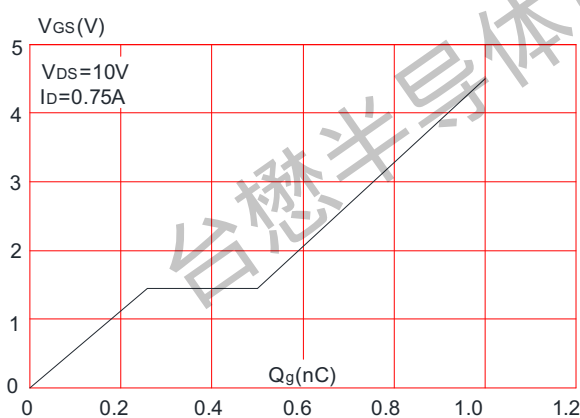
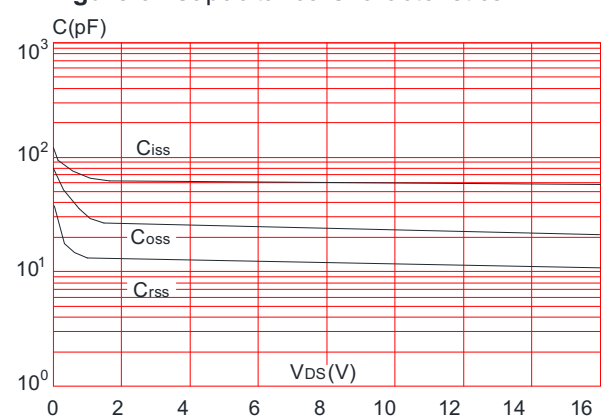


Figure 6: Capacitance Characteristics



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Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

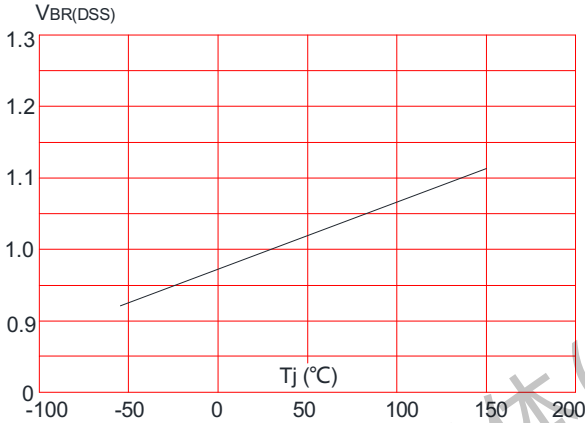


Figure 8: Normalized on Resistance vs. Junction Temperature

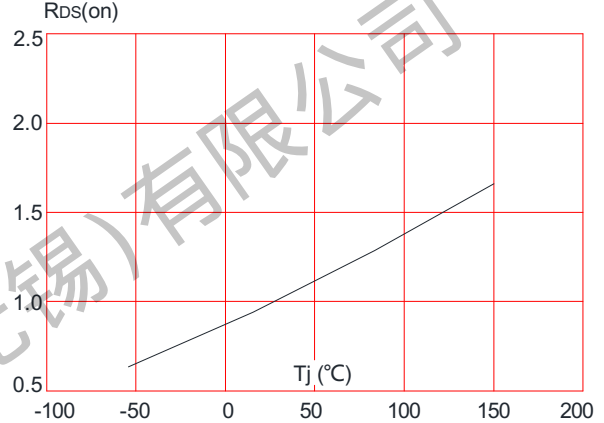


Figure 9: Maximum Safe Operating Area

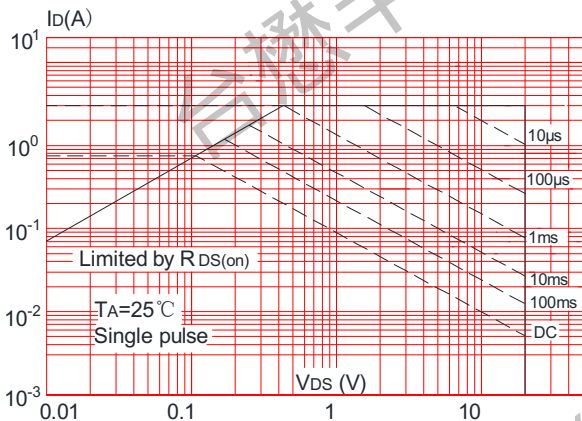


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

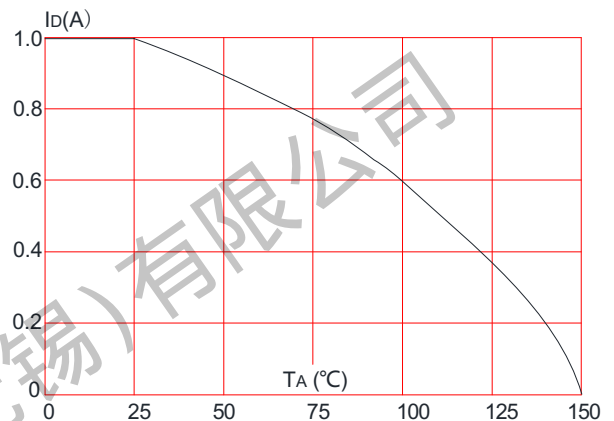
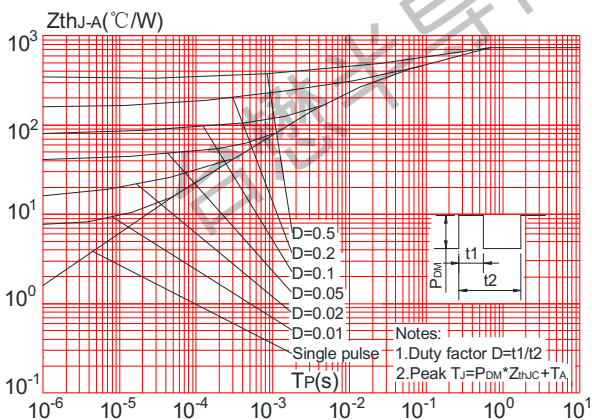


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

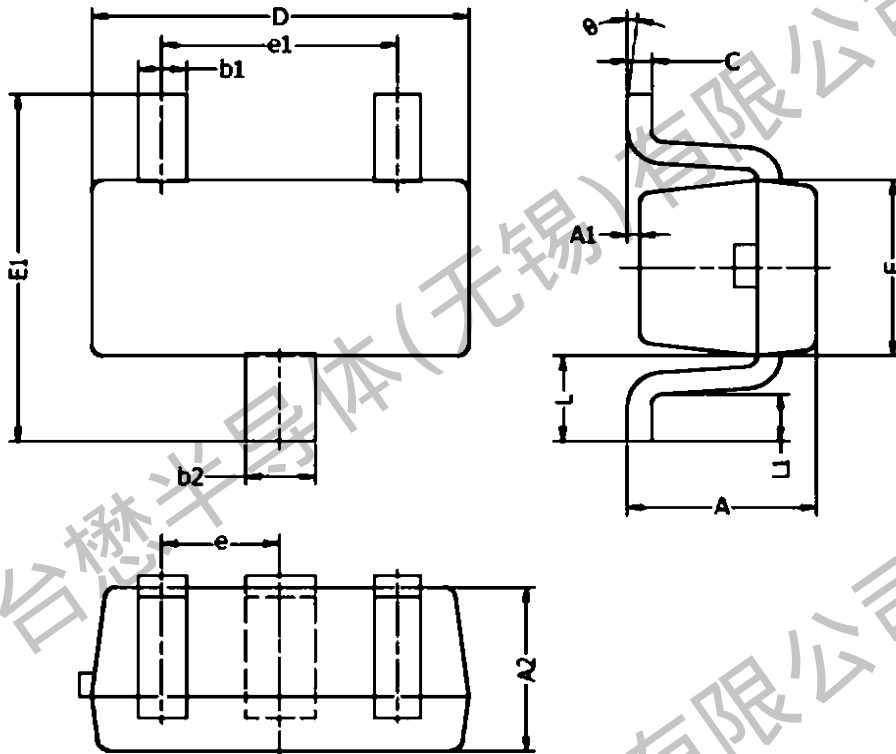




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N-Channel Enhancement Mosfet

Package Mechanical Data:SOT-523



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.70	0.90	0.028	0.035
A1	0.00	0.10	0.000	0.004
A2	0.70	0.80	0.028	0.031
b1	0.15	0.25	0.006	0.010
b2	0.25	0.35	0.010	0.014
c	0.10	0.20	0.004	0.008
D	1.50	1.70	0.059	0.067
E	0.70	0.90	0.028	0.035
E1	1.45	1.75	0.057	0.069
e	0.50 TYP.		0.020 TYP.	
e1	0.90	1.10	0.035	0.043
L	0.40 REF.		0.016 REF.	
L1	0.10	0.30	0.004	0.012
theta	0°	8°	0°	8°

NOTES:

1. Above package outline conforms to JEITA EAJ ED-7500A SC-75A.
2. Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.



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Revision history:

Date	Rev	Description	Page
2023.05.05	23.05	Original	